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leadframe containing a portion that is coplanar with the second side of the die, the first side of the die facing in a direction toward the inside of the cup.

REMARKS

Claims 1-8 are pending in this application, all of which stand rejected. Claim 1 has been amended, and Claims 2-8 depend from Claim 1. Reconsideration is now requested.

Claims 1-8 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Japanese Patent publication No. 9-64421.

Claim 1 has been amended to overcome the rejection. Claim 1 has been amended to add the phrase "the first side of the die facing in a direction toward the inside of the cup". Support for this limitation can be found, for example, in Fig.1 and at page 2, lines 26-29 of the specification and drawings as originally filed. No new matter is added. It is evident from Fig. 1 of Japanese Patent publication No. 9-64421 that neither the first side or second side on which the respective first or second electrical terminals are located face in a direction toward the inside of the cup.

Claims 2-8 depend from and further limit Claim 1 and are therefore allowable over Japanese Patent publication No. 9-64421 for the same reason.

The amendment to the claim is shown in Attachment A.

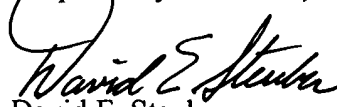
Applicants respectfully submit that Claims 1-8 are allowable. Should the Examiner wish to discuss this case, he is invited to telephone the Applicants' attorney at 408-453-9200.

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Respectfully submitted,



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Attachment A

1. (Amended) A semiconductor package comprising:

a semiconductor die having a first and second sides, a first electrical terminal being located on the first side, at least a second electrical terminal being located on the second side; and

a leadframe in electrical contact with the first terminal, the leadframe being formed in the shape of a cup, the die being located in the cup, at least one lead of the leadframe containing a portion that is coplanar with the second side of the die, the first side of the die facing in a direction toward the inside of the cup.

→ suggest inspection

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